

# PATENT ABSTRACTS OF JAPAN

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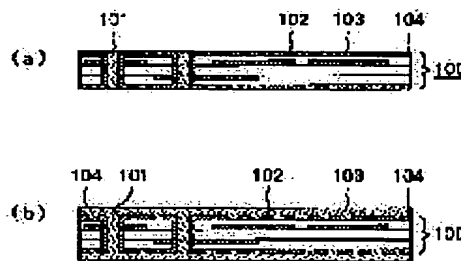
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## (54) BUILDUP MULTILAYER WIRING BOARD AND MANUFACTURE THEREOF

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a built-up multilayer board, which is equipped with a flat inner layer board and high in reliability and a manufacturing method thereof, wherein a specific hole filling process which elongates a board manufacturing process can be dispensed with, and the inner board can be manufactured by filling many plated through-holes of high aspect ratio with various filling material.

**SOLUTION:** A frame-like conductor pattern 104 is formed on a base board wiring layer 102 and the periphery of a board, being isolated electrically from the wiring layer 102 and surrounding the wiring layer 102, a solvent-free fluid high-molecular precursor is placed on the frame-like conductor pattern 104, and after a plated through-hole 101 inside and gaps between wirings are evacuated, the precursor is filled into the plated through-hole and the gap and is cured under a hydrostatic pressure, the plated through-hole 101 is filled up, and the inner board is planarized being kept free of defects.



## LEGAL STATUS

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